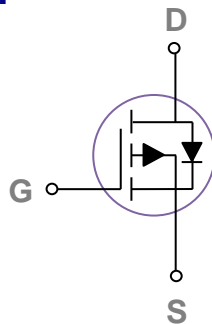
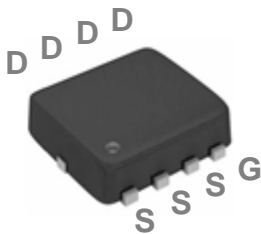


General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

| | | |
|-------|-------|------|
| BVDSS | RDSON | ID |
| -20V | 8.3mΩ | -55A |

PPAK3X3 Pin Configuration



Features

- -20V,-55A, $R_{DS(ON)} = 8.3m\Omega @ V_{GS} = -4.5V$
- Improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for -1.8V Gate Drive Applications

Applications

- Notebook
- Load Switch
- Networking
- Hand-Held Instruments

Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

| Symbol | Parameter | Rating | Units |
|-----------|--|------------|---------------|
| V_{DS} | Drain-Source Voltage | -20 | V |
| V_{GS} | Gate-Source Voltage | ± 10 | V |
| I_D | Drain Current – Continuous ($T_c=25^\circ C$) | -55 | A |
| | Drain Current – Continuous ($T_c=100^\circ C$) | -35 | A |
| I_{DM} | Drain Current – Pulsed ¹ | -220 | A |
| EAS | Single Pulse Avalanche Energy ² | 157 | mJ |
| IAS | Single Pulse Avalanche Current ² | -56 | A |
| P_D | Power Dissipation ($T_c=25^\circ C$) | 51 | W |
| | Power Dissipation – Derate above $25^\circ C$ | 0.41 | W/ $^\circ C$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction to ambient | --- | 62 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction to Case | --- | 2.45 | $^\circ C/W$ |

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|------------|--------------------------------|---|------|------|-----------|---------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=-250\mu A$ | -20 | --- | --- | V |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=-20V, V_{GS}=0V, T_J=25^\circ\text{C}$ | --- | --- | -1 | μA |
| | | $V_{DS}=-16V, V_{GS}=0V, T_J=125^\circ\text{C}$ | --- | --- | -10 | μA |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 10V, V_{DS}=0V$ | --- | --- | ± 100 | nA |

On Characteristics

| | | | | | | |
|--------------|-----------------------------------|--------------------------------|------|------|-----|------------|
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance | $V_{GS}=-4.5V, I_D=-12A$ | --- | 6.9 | 8.3 | m Ω |
| | | $V_{GS}=-2.5V, I_D=-10A$ | --- | 9.4 | 12 | |
| | | $V_{GS}=-1.8V, I_D=-8A$ | --- | 14 | 18 | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}, I_D=-250\mu A$ | -0.3 | -0.6 | -1 | V |
| g_{fs} | Forward Transconductance | $V_{DS}=-10V, I_S=-3A$ | --- | 15 | --- | S |

Dynamic and switching Characteristics

| | | | | | | |
|--------------|-------------------------------------|--|-----|------|------|----------|
| Q_g | Total Gate Charge ^{3, 4} | $V_{DS}=-10V, V_{GS}=-4.5V, I_D=-30A$ | --- | 30 | 45 | nC |
| Q_{gs} | Gate-Source Charge ^{3, 4} | | --- | 4.7 | 7.1 | |
| Q_{gd} | Gate-Drain Charge ^{3, 4} | | --- | 9 | 13.5 | |
| $T_{d(on)}$ | Turn-On Delay Time ^{3, 4} | $V_{DD}=-10V, V_{GS}=-4.5V, R_G=6\Omega, I_D=-30A$ | --- | 15 | 23 | nS |
| T_r | Rise Time ^{3, 4} | | --- | 20 | 30 | |
| $T_{d(off)}$ | Turn-Off Delay Time ^{3, 4} | | --- | 30 | 55 | |
| T_f | Fall Time ^{3, 4} | | --- | 25 | 38 | |
| C_{iss} | Input Capacitance | $V_{DS}=-10V, V_{GS}=0V, F=1\text{MHz}$ | --- | 3300 | 5000 | pF |
| C_{oss} | Output Capacitance | | --- | 420 | 630 | |
| C_{rSS} | Reverse Transfer Capacitance | | --- | 370 | 560 | |
| R_g | Gate resistance | $V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$ | --- | 5 | --- | Ω |

Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|----------|---------------------------|--|------|------|------|------|
| I_S | Continuous Source Current | $V_G=V_D=0V, \text{Force Current}$ | --- | --- | -55 | A |
| I_{SM} | Pulsed Source Current | | --- | --- | -110 | A |
| V_{SD} | Diode Forward Voltage | $V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$ | --- | --- | -1 | V |

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=-25V, V_{GS}=-10V, L=0.1\text{mH}, I_{AS}=-56A, \text{Starting } T_J=25^\circ\text{C}$
3. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

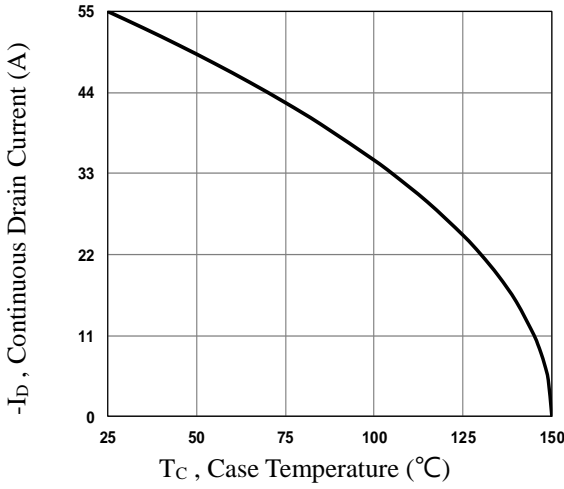


Fig.1 Continuous Drain Current vs. T_c

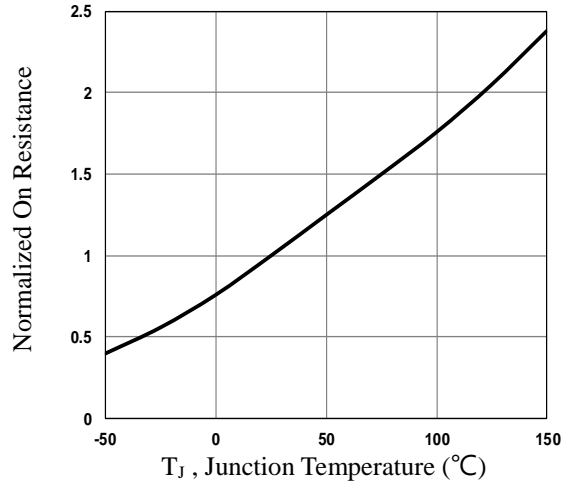


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

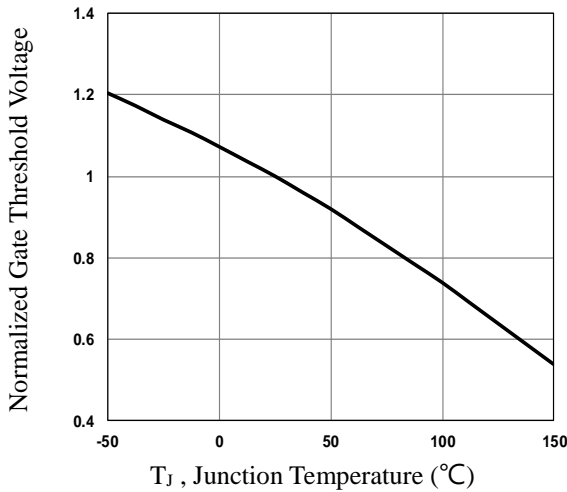


Fig.3 Normalized V_{th} vs. T_j

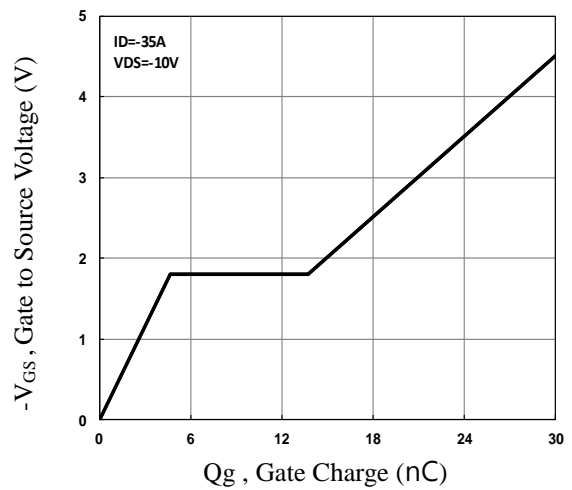


Fig.4 Gate Charge Waveform

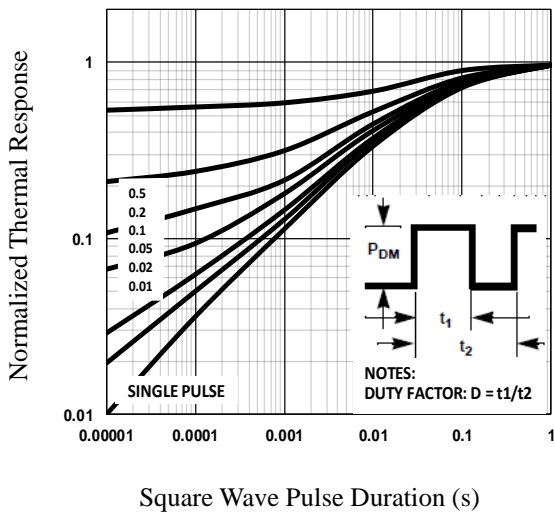


Fig.5 Normalized Transient Impedance

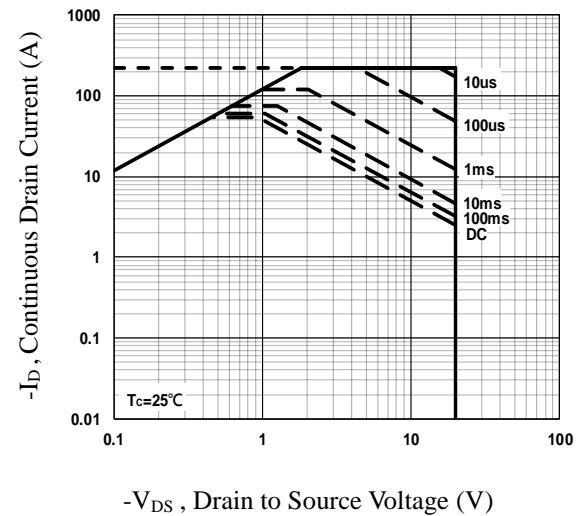


Fig.6 Maximum Safe Operation Area

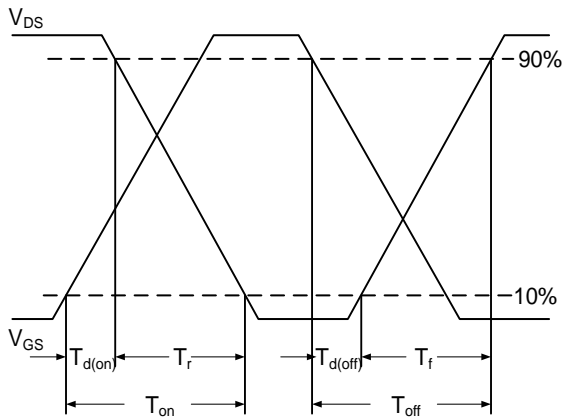


Fig.7 Switching Time Waveform

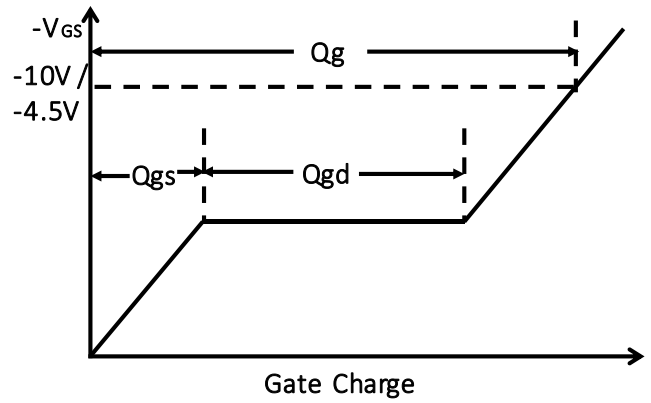
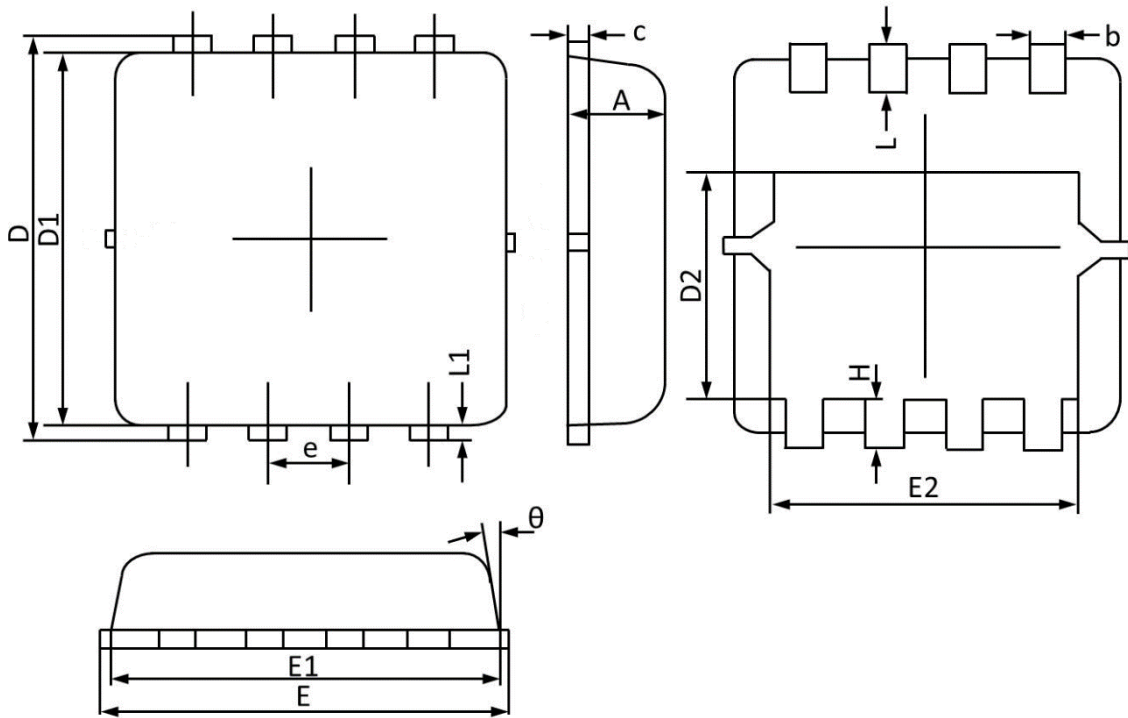


Fig.8 Gate Charge Waveform

PPAK3x3 PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | MAX | MIN | MAX | MIN |
| A | 0.900 | 0.700 | 0.035 | 0.028 |
| b | 0.350 | 0.250 | 0.014 | 0.010 |
| c | 0.250 | 0.100 | 0.010 | 0.004 |
| D | 3.500 | 3.050 | 0.138 | 0.120 |
| D1 | 3.200 | 2.900 | 0.126 | 0.114 |
| D2 | 1.950 | 1.350 | 0.077 | 0.053 |
| E | 3.400 | 3.000 | 0.134 | 0.118 |
| E1 | 3.300 | 2.900 | 0.130 | 0.114 |
| E2 | 2.600 | 2.350 | 0.102 | 0.093 |
| e | 0.65BSC | | 0.026BSC | |
| H | 0.750 | 0.300 | 0.030 | 0.012 |
| L | 0.600 | 0.300 | 0.024 | 0.012 |
| L1 | 0.200 | 0.060 | 0.008 | 0.002 |
| θ | 14° | 6° | 14° | 6° |